
GLOSSARY OF TECHNICAL TERMS

This glossary of technical terms contains definitions of certain terms used in this prospectus in connection with the business of the Group. As such, these terms and their meanings may not correspond to standard industry meaning or usage of these terms.

“auto insertion”	a process where axial and radial leaded components such as capacitors and resistors are inserted into the printed circuit boards using high speed machines
“automatic optical inspection”	a process of automatic detection, inspection, retrieval and record of the open/short defects of PCB circuitry by using optical technology to ensure the functional quality of PCB products
“blind and buried via”	PCBs manufactured with inner layer(s) that consists of electrolytic copper plated via through holes and involves sequential lamination process to laminate the inner layer(s) to form the PCB, thus it will have via holes buried inside as well as via holes in blind form below the surface of the PCB
“capacitor”	an active device for charging and storing electricity
“EMS”	acronym for “electronics manufacturing services”
“Entek”	a type of final surface finishing which contains anti-tarnish chemicals
“fine line”	PCBs with circuit track/line widths of 0.002 inch to 0.003 inch line width
“Getek”	a radio transmission application material
“gold tap plating”	an electrolytic gold plating process used to produce the required gold deposit selectively on the tap area of PCB for electrical connection with other devices
“high Tg material”	a high thermal/heat resistance material
“HMLV”	acronym for “high mix low volume”, which is used to describe the mixture of a number of different products in small volume quantities per batch or order

GLOSSARY OF TECHNICAL TERMS

“hot air levelling”	a manufacturing process for producing the required tin-lead solder deposit coating on the PCBs under high temperature condition and by using hot air blowing pressure to level the solder during operation in order to achieve even coating
“immersion silver” or “immersion gold”	a chemical process used to produce silver or gold deposit coating on PCB products
“ISO”	acronym for a series of quality management and quality assurance standards published by the International Organisation for Standardisation, a non-government organisation based in Geneva, Switzerland, for assessing the quality systems of business organisations
“ISO 9001/ISO 9002”	a constituent part of the ISO 9000 series which covers the areas of management responsibility; quality system; contract review; document and data control; purchasing; control of customer’s supplied-products, product identification and traceability; process control; inspection and testing; measuring and equipment testing; control of non-conforming product; corrective and preventive action; handling; storage; packaging preservation and delivery; control of quality records; internal quality audits; training; servicing and statistical techniques
“ISO 9002”	the certification for an internationally recognised standard for product quality assurance
“laminates”	a laminate is a basic raw material of a PCB. It consists of a sheet of fully cured resin which is covered on both sides with copper foil. The resin serves as an electrical insulator for the PCB and the copper foil produces the necessary electrical circuitry for the PCB
“microvia technology”	a technology used in producing holes on PCBs, whose size is equal to or less than 0.006 inch, which is 50% to 70% smaller than those of conventional PCB products
“OEM”	acronym for “original equipment manufacturer”
“PC”	acronym for “personal computers”
“PCB(s)”	acronym for “printed circuit board(s)”

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“prepregs”	a prepreg is a basic raw material of a PCB. It is an uncured sheet of resin that is used for bonding inner layers together to form a basic multilayer PCB
“QS 9000”	an extension of ISO 9000 certification which conforms to the quality requirements laid down by the automotive industry in the US
“R&D”	acronym for “research and development”
“Rogers material”	a microwave transmission application